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Docket No.: M4065.0127/P127-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kie Y. Ahn, et al

Application No.: 09/660,324 ✓

Group Art Unit: 2581 ✓

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE
PACKAGING WITH INTEGRATED
PASSIVE COMPONENTS AND METHOD
OF MAKING

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Notice of Non-Compliant Amendment dated December 22, 2003, enclosed is a complete listing of claims for the above reference patent application.

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